THE DATASHEET OF

74AVCBH324245ZKER

SN74AVCBH324245
32-BIT DUAL-SUPPLY BUS TRANSCEIVER WITH CONFIGURABLE VOLTAGE TRANSLATION AND 3-STATE OUTPUTS

SCES550B – FEBRUARY 2004 – REVISED JUNE 2005

FEATURES

- **Member of the Texas Instruments Widebus+™ Family**
- **DOC™ Circuitry Dynamically Changes Output Impedance, Resulting in Noise Reduction Without Speed Degradation**
- **Dynamic Drive Capability Is Equivalent to Standard Outputs With I_{OH} and I_{OL} of**
  - **– ±24 mA at 3-V V_{CC}**
  - **– ±15 mA at 2.3-V V_{CC}**
  - **– ±9 mA at 1.65-V V_{CC}**
  - **– ±6 mA at 1.4-V V_{CC}**
- **Control Inputs V_{IH}/V_{IL} Levels Are Referenced to V_{CCB} Voltage**
- **If Either V_{CC} Input Is at GND, Both Ports Are in the High-Impedance State**
- **Inputs/Outputs Can Tolerate up to 4.6 V, Which Allows Mixed-Voltage-Mode Data Communications**
- **I_{off} Supports Partial-Power-Down Mode Operation**
- **Fully Configurable Dual-Rail Design Allows Each Port to Operate Over Full 1.4-V to 3.6-V Power-Supply Range**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II**
- **ESD Protection Exceeds JESD 22**
  - **– 2000-V Human-Body Model (A114-A)**
  - **– 200-V Machine Model (A115-A)**
  - **– 1000-V Charged-Device Model (C101)**

DESCRIPTION/ORDERING INFORMATION

This 32-bit noninverting bus transceiver uses two separate configurable power-supply rails. The A port is designed to track V_{CCA}. V_{CCA} accepts any supply voltage from 1.4 V to 3.6 V. The B port is designed to track V_{CCB}. V_{CCB} accepts any supply voltage from 1.4 V to 3.6 V. This allows for universal low-voltage bidirectional translation between any of the 1.5-V, 1.8-V, 2.5-V, and 3.3-V voltage nodes.

The SN74AVCBH324245 is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ($\overline{OE}$) input is used to disable the outputs, so the buses effectively are isolated.

The SN74AVCBH324245 is designed so that the control pins (1DIR, 2DIR, 1$\overline{OE}$, and 2$\overline{OE}$) are supplied by V_{CCB}.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CCB} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. If either V_{CC} input is at GND, both ports are in the high-impedance state.

ORDERING INFORMATION

T_A	PACKAGE(1)		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	LFBGA – GKE	Tape and reel	SN74AVCBH324245KR	WN4245
	LFBGA – ZKE	Tape and reel	74AVCBH324245ZKER	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

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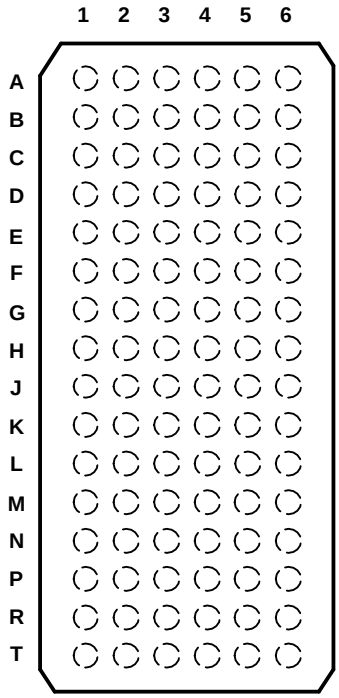
GKE PACKAGE
(TOP VIEW)



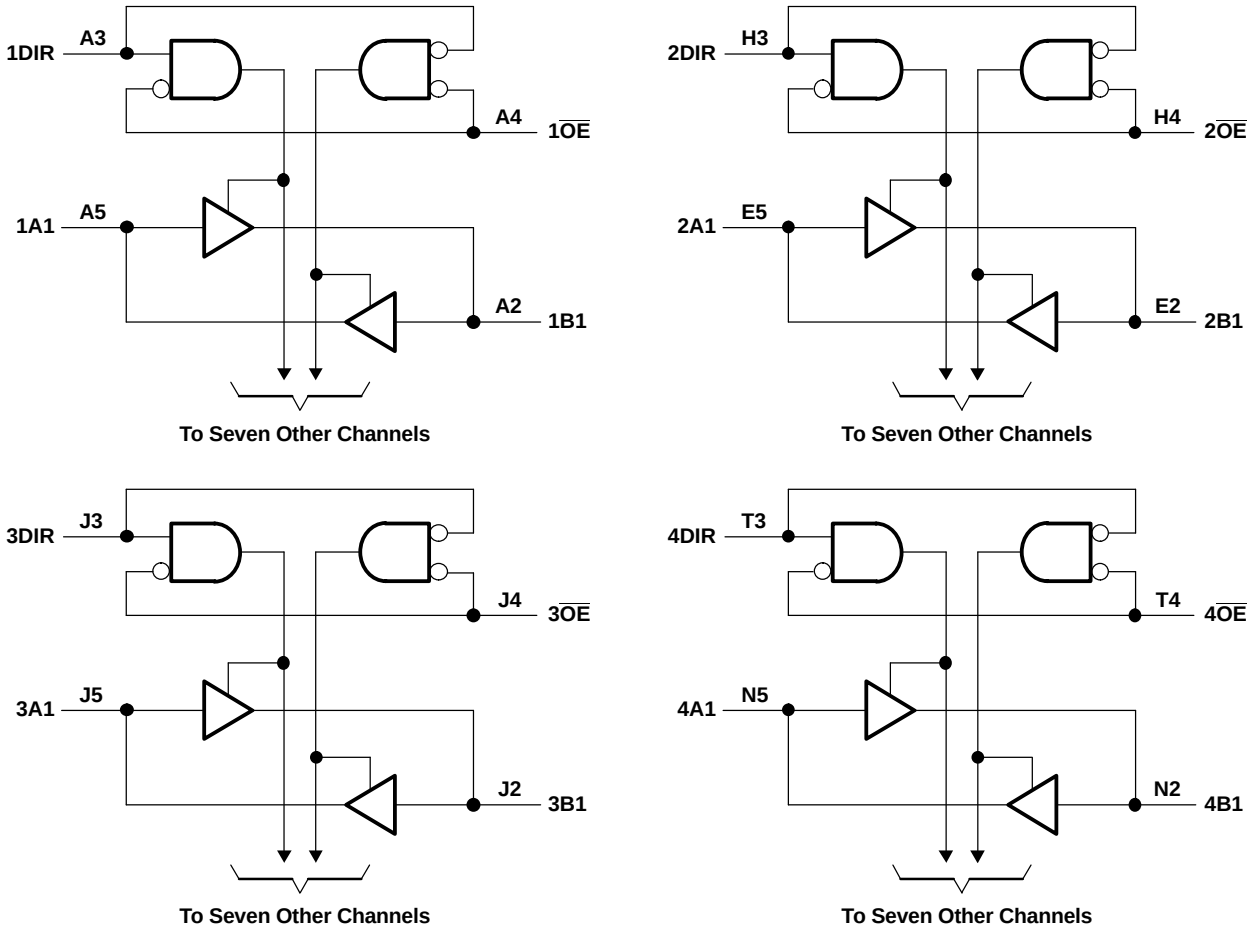
TERMINAL ASSIGNMENTS

	1	2	3	4	5	6
A	1B2	1B1	1DIR	1$\overline{OE}$	1A1	1A2
B	1B4	1B3	GND	GND	1A3	1A4
C	1B6	1B5	V_{CCB}	V_{CCA}	1A5	1A6
D	1B8	1B7	GND	GND	1A7	1A8
E	2B2	2B1	GND	GND	2A1	2A2
F	2B4	2B3	V_{CCB}	V_{CCA}	2A3	2A4
G	2B6	2B5	GND	GND	2A5	2A6
H	2B7	2B8	2DIR	2$\overline{OE}$	2A8	2A7
J	3B2	3B1	3DIR	3$\overline{OE}$	3A1	3A2
K	3B4	3B3	GND	GND	3A3	3A4
L	3B6	3B5	V_{CCB}	V_{CCA}	3A5	3A6
M	3B8	3B7	GND	GND	3A7	3A8
N	4B2	4B1	GND	GND	4A1	4A2
P	4B4	4B3	V_{CCB}	V_{CCA}	4A3	4A4
R	4B6	4B5	GND	GND	4A5	4A6
T	4B7	4B8	4DIR	4$\overline{OE}$	4A8	4A7

FUNCTION TABLE (EACH 8-BIT SECTION)

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CCA} V_{CCB}	Supply voltage range		–0.5	4.6	V
V_I	Input voltage range(2)	I/O port (A port)	–0.5	4.6	V
		I/O port (B port)	–0.5	4.6	
		Control inputs	–0.5	4.6	
V_O	Voltage range applied to any output in the high-impedance or power-off state(2)	A port	–0.5	4.6	V
		B port	–0.5	4.6	
V_O	Voltage range applied to any output in the high or low state(2)(3)	A port	–0.5	V_{CCA} + 0.5	V
		B port	–0.5	V_{CCB} + 0.5	
I_{IK}	Input clamp current	V_I < 0		–50	mA
I_{OK}	Output clamp current	V_O < 0		–50	mA
I_O	Continuous output current			±50	mA
	Continuous current through each V_{CCA}, V_{CCB}, or GND			±100	mA
θ_{JA}	Package thermal impedance(4)	GKE/ZKE package		40	°C/W
T_{stg}	Storage temperature range		–65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input voltage and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
(3) The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current rating is observed.
(4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions[1][2][3]

			V_{CCI}	V_{CCO}	MIN	MAX	UNIT
V_{CCA}	Supply voltage				1.4	3.6	V
V_{CCB}	Supply voltage				1.4	3.6	V
V_{IH}	High-level input voltage	Data inputs	1.4 V to 1.95 V		V_{CCI} × 0.65	3.6	V
			1.95 V to 2.7 V		1.7	3.6	
			2.7 V to 3.6 V		2	3.6	
V_{IL}	Low-level input voltage	Data inputs	1.4 V to 1.95 V		0	V_{CCI} × 0.35	V
			1.95 V to 2.7 V		0	0.7	
			2.7 V to 3.6 V		0	0.8	
V_{IH}	High-level input voltage	Control inputs (referenced to V_{CCB})	1.4 V to 1.95 V		V_{CCB} × 0.65	V_{CCB}	V
			1.95 V to 2.7 V		1.7	V_{CCB}	
			2.7 V to 3.6 V		2	V_{CCB}	
V_{IL}	Low-level input voltage	Control inputs (referenced to V_{CCB})	1.4 V to 1.95 V		0	V_{CCB} × 0.35	V
			1.95 V to 2.7 V		0	0.7	
			2.7 V to 3.6 V		0	0.8	
V_O	Output voltage				0	V_{CCO}	V
I_{OH}	High-level output current			1.4 V to 1.6 V		–2	mA
				1.65 V to 1.95 V		–4	
				2.3 V to 2.7 V		–8	
				3 V to 3.6 V		–12	
I_{OL}	Low-level output current			1.4 V to 1.6 V		2	mA
				1.65 V to 1.95 V		4	
				2.3 V to 2.7 V		8	
				3 V to 3.6 V		12	
$\Delta t/\Delta v$	Input transition rise or fall rate					5	ns/V
T_A	Operating free-air temperature				–40	85	°C

(1) V_{CCI} is the V_{CC} associated with the data input port.
(2) V_{CCO} is the V_{CC} associated with the output port.
(3) All unused data inputs of the device must be held at V_{CCI} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics(1)

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		V_{CCA}	V_{CCB}	MIN	TYP(2)	MAX	UNIT
V_{OH}		I_{OH} = –100 µA,	$V_I = V_{IH}$	1.4 V to 3.6 V	1.4 V to 3.6 V	V_{CCO} – 0.2			V
		I_{OH} = –2 mA,	$V_I = V_{IH}$	1.4 V	1.4 V	1.05			
		I_{OH} = –4 mA,	$V_I = V_{IH}$	1.65 V	1.65 V	1.2			
		I_{OH} = –8 mA,	$V_I = V_{IH}$	2.3 V	2.3 V	1.75			
		I_{OH} = –12 mA,	$V_I = V_{IH}$	3 V	3 V	2.3			
V_{OL}		I_{OH} = 100 µA,	$V_I = V_{IL}$	1.4 V to 3.6 V	1.4 V to 3.6 V			0.2	V
		I_{OH} = 2 mA,	$V_I = V_{IL}$	1.4 V	1.4 V			0.35	
		I_{OH} = 4 mA,	$V_I = V_{IL}$	1.65 V	1.65 V			0.45	
		I_{OH} = 8 mA,	$V_I = V_{IL}$	2.3 V	2.3 V			0.55	
		I_{OH} = 12 mA,	$V_I = V_{IL}$	3 V	3 V			0.7	
V_{OH}		I_{OHD} = –6 mA,	$V_I = V_{IH}$	1.4 V	1.4 V	1.05			V
		I_{OHD} = –9 mA,	$V_I = V_{IH}$	1.65 V	1.65 V	1.2			
		I_{OHD} = –15 mA,	$V_I = V_{IH}$	2.3 V	2.3 V	1.75			
		I_{OHD} = –24 mA,	$V_I = V_{IH}$	3 V	3 V	2.3			
V_{OL}		I_{OHD} = 6 mA,	$V_I = V_{IL}$	1.4 V	1.4 V			0.35	V
		I_{OHD} = 9 mA,	$V_I = V_{IL}$	1.65 V	1.65 V			0.45	
		I_{OHD} = 15 mA,	$V_I = V_{IL}$	2.3 V	2.3 V			0.55	
		I_{OHD} = 24 mA,	$V_I = V_{IL}$	3 V	3 V			0.7	
I_I	Control inputs	$V_I = V_{CCB}$ or GND		1.4 V to 3.6 V	3.6 V			±2.5	µA
I_{BHL}(3)		V_I = 0.49 V		1.4 V	1.4 V		11		µA
		V_I = 0.57 V		1.65 V	1.65 V	25			
		V_I = 0.7 V		2.3 V	2.3 V	45			
		V_I = 0.8 V		3 V	3 V	75			
I_{BHH}(4)		V_I = 0.49 V		1.4 V	1.4 V		–11		µA
		V_I = 1.07 V		1.65 V	1.65 V	–25			
		V_I = 1.7 V		2.3 V	2.3 V	–45			
		V_I = 2 V		3 V	3 V	–75			
I_{BHLO}(5)		V_I = 0 to V_{CC}		1.6 V	1.6 V	100			µA
				1.95 V	1.95 V	200			
				2.7 V	2.7 V	300			
				3.6 V	3.6 V	525			
I_{BHHO}(6)		V_I = 0 to V_{CC}		1.6 V	1.6 V	–100			µA
				1.95 V	1.95 V	–200			
				2.7 V	2.7 V	–300			
				3.6 V	3.6 V	–525			

(1) V_{CCO} is the V_{CC} associated with the output port.
(2) All typical values are at T_A = 25°C.
(3) The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL} max.
(4) The bus-hold circuit can source at least the minimum high sustaining current at V_{IH} min. I_{BHH} should be measured after raising V_{IN} to V_{CC} and then lowering it to V_{IH} min.
(5) An external driver must source at least I_{BHLO} to switch this node from low to high.
(6) An external driver must sink at least I_{BHHO} to switch this node from high to low.

Electrical Characteristics[1][2] (continued)

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		V_{CCA}	V_{CCB}	MIN	TYP[3]	MAX	UNIT
I_{off}	A port	V_I or V_O = 0 to 3.6 V		0 V	0 to 3.6 V			±10	µA
	B port			0 to 3.6 V	0 V			±10	
I_{OZ}[4]	A or B port	V_O = V_{CCO} or GND, V_I = V_{CCI} or GND	$\overline{OE}$ = V_{IH}	3.6 V	3.6 V			±12.5	µA
	B port		$\overline{OE}$ = don't care	0 V	3.6 V			±12.5	
	A port			3.6 V	0 V			±12.5	
I_{CCA}		V_I = V_{CCI} or GND,	I_O = 0	1.6 V	1.6 V			40	µA
				1.95 V	1.95 V			40	
				2.7 V	2.7 V			60	
				0 V	3.6 V			–80	
				3.6 V	0 V			80	
				3.6 V	3.6 V			80	
I_{CCB}		V_I = V_{CCI} or GND,	I_O = 0	1.6 V	1.6 V			40	µA
				1.95 V	1.95 V			40	
				2.7 V	2.7 V			60	
				0 V	3.6 V			80	
				3.6 V	0 V			–80	
				3.6 V	3.6 V			80	
C_i	Control inputs	V_I = 3.3 V or GND		3.3 V	3.3 V		4		pF
C_{io}	A or B ports	V_O = 3.3 V or GND		3.3 V	3.3 V		5		pF

(1) V_{CCO} is the V_{CC} associated with the output port.
(2) V_{CCI} is the V_{CC} associated with the input port.
(3) All typical values are at T_A = 25°C.
(4) For I/O ports, the parameter I_{OZ} includes the input leakage current.

Switching Characteristics

over recommended operating free-air temperature range, V_{CCA} = 1.5 V ± 0.1 V (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CCB} = 1.5 V ± 0.1 V		V_{CCB} = 1.8 V ± 0.15 V		V_{CCB} = 2.5 V ± 0.2 V		V_{CCB} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A	B	1.7	6.7	1.9	6.4	1.8	5.5	1.5	5.8	ns
	B	A	1.8	6.8	1.7	6.2	1.6	5.9	1.5	5.9	
t_{en}	$\overline{OE}$	A	2.1	9	2.9	9.8	3.2	10	3	9.8	ns
		B	2.5	8.4	2.4	8	2.3	7.6	2.2	7.5	
t_{dis}	$\overline{OE}$	A	2.1	7.1	2.3	6.4	1.7	5.1	1.6	4.8	ns
		B	2.2	6.9	1.8	6.4	1.1	5.8	1.8	5.7	

Switching Characteristics

over recommended operating free-air temperature range, V_{CCA} = 1.8 V ± 0.15 V (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CCB} = 1.5 V ± 0.1 V		V_{CCB} = 1.8 V ± 0.15 V		V_{CCB} = 2.5 V ± 0.2 V		V_{CCB} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A	B	1.7	6.4	1.8	6	1.7	4.7	1.6	4.3	ns
	B	A	2	6.6	1.8	6	1.8	5.6	1.8	5.5	
t_{en}	$\overline{OE}$	A	1.8	7.6	2.6	7.7	2.6	7.6	2.6	7.4	ns
		B	2.5	8.2	2.5	7.5	2.4	7.4	2.3	7.2	
t_{dis}	$\overline{OE}$	A	1.8	7	2.5	6.3	1.8	4.7	1.7	4.4	ns
		B	2.5	6.7	2.3	6.1	2.2	5.5	1.3	5.3	

Switching Characteristics

over recommended operating free-air temperature range, V_{CCA} = 2.5 V ± 0.2 V (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CCB} = 1.5 V ± 0.1 V		V_{CCB} = 1.8 V ± 0.15 V		V_{CCB} = 2.5 V ± 0.2 V		V_{CCB} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A	B	1.6	6	1.8	5.6	1.5	4	1.5	3.4	ns
	B	A	1.7	5.4	1.7	4.6	1.5	4	1.5	3.7	
t_{en}	$\overline{OE}$	A	1.7	5.7	2.2	5.5	2.2	5.3	2.2	5.1	ns
		B	3.1	6.1	2.5	5.6	2.2	5.3	1.9	4.2	
t_{dis}	$\overline{OE}$	A	1.2	5.8	1.9	5	1.4	3.6	1.3	3.3	ns
		B	2.4	6	3	5.2	1.4	3.6	1.2	3	

Switching Characteristics

over recommended operating free-air temperature range, V_{CCA} = 3.3 V ± 0.3 V (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CCB} = 1.5 V ± 0.1 V		V_{CCB} = 1.8 V ± 0.15 V		V_{CCB} = 2.5 V ± 0.2 V		V_{CCB} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A	B	1.5	5.9	1.7	5.4	1.5	3.7	1.4	3.1	ns
	B	A	1.5	5.8	1.5	4.2	1.5	3.3	1.4	3.1	
t_{en}	$\overline{OE}$	A	1.6	4.9	2	4.5	2	4.3	1.9	4.1	ns
		B	2	5.1	2	4.6	2.2	5.2	1.9	4.1	
t_{dis}	$\overline{OE}$	A	1.3	6.9	2.1	5.5	1.6	3.8	1.5	3.5	ns
		B	2.3	5.5	1.9	4.5	1.3	3.5	1.2	3.5	

Operating Characteristics

V_{CCA} and V_{CCB} = 3.3 V, T_A = 25°C

PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pdA} (V_{CCA})	Power-dissipation capacitance per transceiver, A-port input, B-port output	Outputs enabled	C_L = 0, f = 10 MHz	14	pF
		Outputs disabled		7	
	Power-dissipation capacitance per transceiver, B-port input, A-port output	Outputs enabled		20	
		Outputs disabled		7	
C_{pdB} (V_{CCB})	Power-dissipation capacitance per transceiver, A-port input, B-port output	Outputs enabled	C_L = 0, f = 10 MHz	20	pF
		Outputs disabled		7	
	Power-dissipation capacitance per transceiver, B-port input, A-port output	Outputs enabled		14	
		Outputs disabled		7	

Output Description

The DOC™ circuitry is implemented, which, during the transition, initially lowers the output impedance to effectively drive the load and, subsequently, raises the impedance to reduce noise. Figure 1 shows typical V_{OL} vs I_{OL} and V_{OH} vs I_{OH} curves to illustrate the output impedance and drive capability of the circuit. At the beginning of the signal transition, the DOC circuit provides a maximum dynamic drive that is equivalent to a high-drive standard-output device. For more information, refer to the TI application reports, *AVC Logic Family Technology and Applications*, literature number SCEA006, and *Dynamic Output Control (DOC™) Circuitry Technology and Applications*, literature number SCEA009.

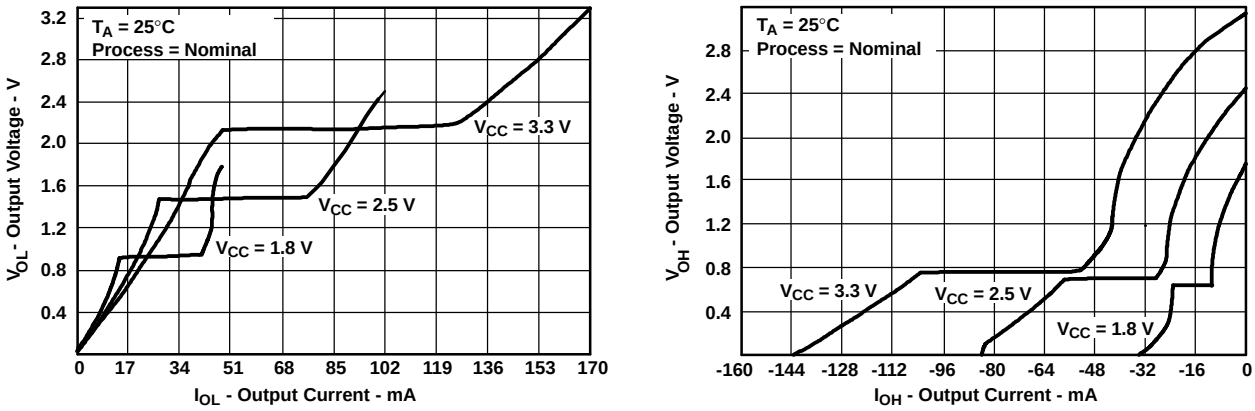
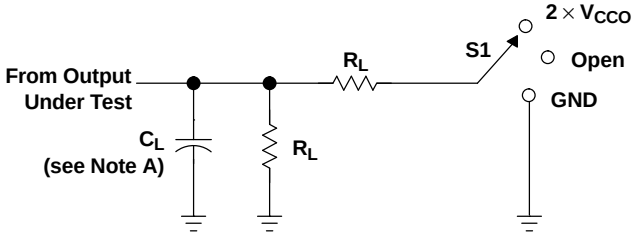


Figure 1. Typical Output Voltage vs Output Current

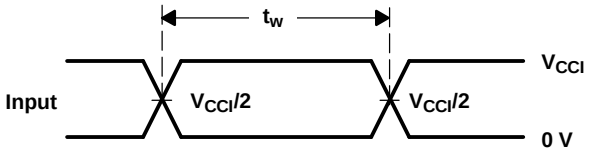
PARAMETER MEASUREMENT INFORMATION



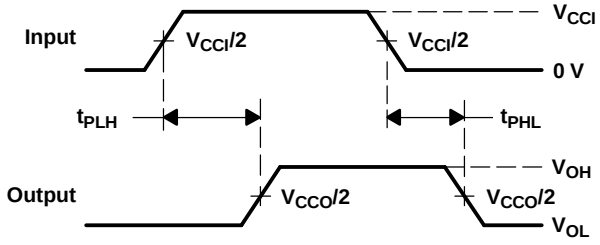
TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CCO}$
t_{PHZ}/t_{PZH}	GND

LOAD CIRCUIT

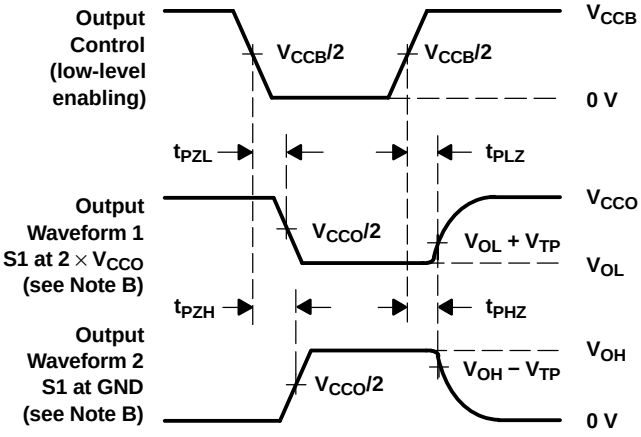
V_{CCO}	C_L	R_L	V_{TP}
1.5 V ± 0.1 V	15 pF	2 kΩ	0.1 V
1.8 V ± 0.15 V	30 pF	1 kΩ	0.15 V
2.5 V ± 0.2 V	30 pF	500 Ω	0.15 V
3.3 V ± 0.3 V	30 pF	500 Ω	0.3 V



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, dv/dt ≥ 1 V/ns.
D. The outputs are measured one at a time, with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. t_{PLH} and t_{PHL} are the same as t_{pd}.
H. V_{CCI} is the V_{CC} associated with the input port.
I. V_{CCO} is the V_{CC} associated with the output port.

Figure 2. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
74AVCBH324245ZKER	ACTIVE	LFBGA	ZKE	96	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR	-40 to 85	WN4245	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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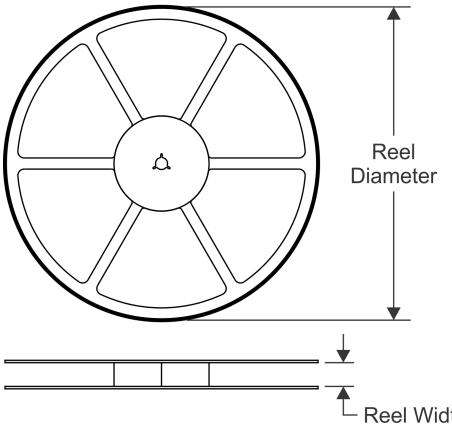
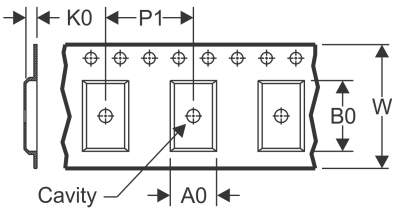
TAPE AND REEL INFORMATION

REEL DIMENSIONS

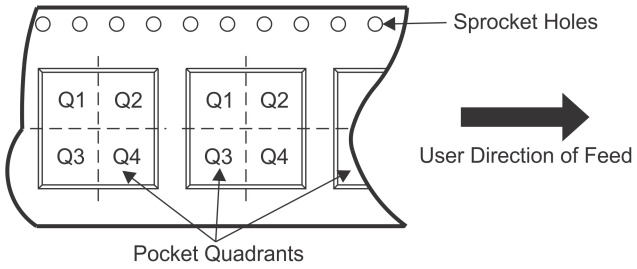


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

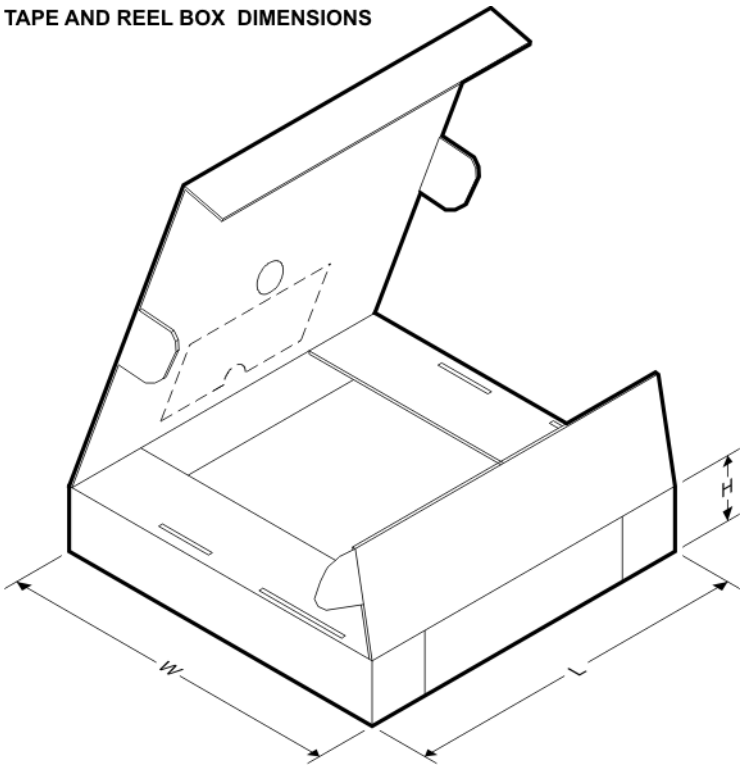
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74AVCBH324245ZKER	LFBGA	ZKE	96	1000	330.0	24.4	5.7	13.7	2.0	8.0	24.0	Q1

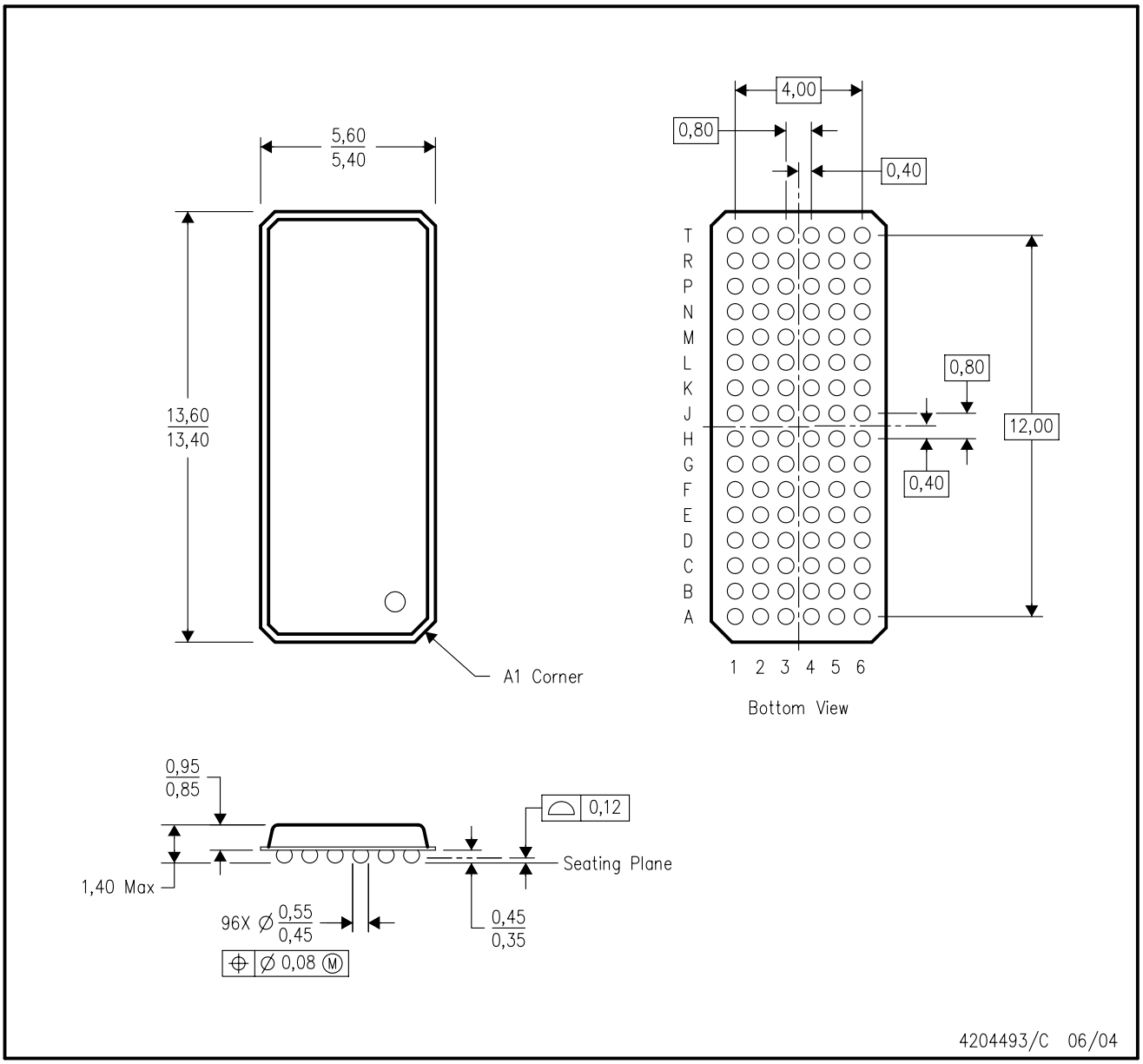
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74AVCBH324245ZKER	LFBGA	ZKE	96	1000	336.6	336.6	41.3

ZKE (R–PBGA–N96) PLASTIC BALL GRID ARRAY



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Falls within JEDEC MO–205 variation CC.
D. This package is lead–free. Refer to the 96 GKE package (drawing 4188953) for tin–lead (SnPb).

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